



Final Product/Process Change Notification

Document #:FPCN26917XC

Issue Date: 17 Aug 2026

Title of Change:	Addition of Manufacturing Site and Wafer Size for T10-80V MOSFET Technology at onsemi East Fishkill, United States
Proposed First Ship date:	24 Nov 2026 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code
Change Category:	Wafer Fab Change, Test Change
Change Sub-Category(s):	Manufacturing Site Addition, Addition of 12-inch wafers from EFK
Sites Affected:	
onsemi Sites	External Foundry/Subcon Sites
onsemi, East Fishkill	None

Description and Purpose:

onsemi wishes to inform customers that we have qualified an additional manufacturing site and wafer size for T10 80-volt MOSFET products. This change supports additional manufacturing capacity and supply continuity through qualification of onsemi East Fishkill, New York, USA, for wafer fabrication, wafer probing, backgrind, and backmetal processing. In addition, 300 mm wafer manufacturing will be added alongside the existing 200 mm wafer process.

There are no changes to electrical characteristics or part numbers as a result of this change.

	Before	After
Wafer fabrication site	onsemi Aizu, Japan	onsemi Aizu, Japan onsemi East Fishkill ,US
Wafer size	200mm	200mm 300mm
Wafer probe site	onsemi Seremban, Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US
Backgrind Backmetal site	onsemi Seremban, Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US



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Reliability Data Summary:

QV DEVICE NAME: NVBLS0D8N08XTXG

RMS: 104681

PACKAGE: TOLL

Test	Specification	Condition	Interval	Result
High Temperature Reverse Bias	JESD22-A108	Ta= _175_ °C, _100_ % max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta= _175_ °C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 175C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NTBLS0D8N08XTXG	#NONE	NVBLS0D8N08XTXG